

JUL 17 2003

TRANSMITTAL LETTER

(General - Patent Pending)

Docket No.

HIZ.003D2

In Re Application Of:

Takashi Ohsumi

Serial No.

09/920,713 /

Filing Date

August 3, 2001

Examiner

Fernando Toled

Group Art Unit

2823

Title: **A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS (As Amended)**

TO THE COMMISSIONER FOR PATENTS:

Transmitted herewith is:

Request for Reconsideration

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in the above identified application.

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50-0238


Signature

Dated: July 17, 2003

ANDREW J. TELESZ, JR.
REG. NO. 33,581

VOLENTINE FRANCO, P.L.L.C.
12200 SUNRISE VALLEY DRIVE, SUITE 150
RESTON, VA 20191

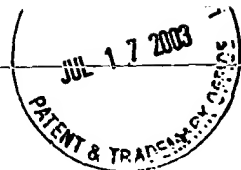
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Serial No. 09/920,713

IIZ.003D2

Request for Reconsideration dated July 17, 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of

Takashi Ohsumi

Group Art Unit: 2823

Serial No.: 09/920,713

Examiner: Fernando Toledo

Filed: August 3, 2001

FOR: A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS
INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS
(As Amended)

REQUEST FOR RECONSIDERATION

U.S. Patent and Trademark Office
2011 South Clark Place
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Crystal Plaza Two, Lobby, Room 1B03
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Date: July 17, 2003

Sir:

In response to the Final Office Action dated April 17, 2003, the following remarks
are respectfully submitted in connection with the above identified application.

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